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## TIDA-000801

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer	Alternate PartNumber	Alternate Manufacturer
!PCB1	1		Printed Circuit Board		TIDA-00801	Any	-	-
C1, C15	2	10uF	CAP, CERM, 10 μF, 50 V, +/- 10%, X7R, 2220	2220	CGA9N3X7R1H106K23 0KB	TDK		
C3 C4, C8	1 2	220uF 1uF	CAP, AL, 220 µF, 63 V, +/- 20%, 0.26 ohm, SMD CAP, CERM, 1 µF, 25 V, +/- 5%, X7R, 1206_190	SMT Radial H13 1206_190	EEE-TK1J221AQ CL31B105JAHNNNE	Panasonic Samsung Electro-Mechanics		
C6, C7	2	560uF	CAP, AL, 560 µF, 50 V, +/- 20%, 0.05 ohm, TH	D12.5xL25mm	EEU-FC1H561	Panasonic		
C9, C19, C20	3	100uF	CAP, CERM, 100 μF, 10 V, +/- 20%, X5R, 1210	1210	LMK325ABJ107MMHT	Taiyo Yuden		
C10, C21	2	1uF	CAP, CERM, 1 µF, 25 V, +/- 10%, X7R, 1206 CAP, CERM, 47 pF, 50 V, +/- 5%, C0G/NP0, 0603	1206 0603	C1206C105K3RACTU GRM1885C1H470JA01	Kemet MuRata		
C12, C27	2	47pF	·		D			
C13 C14, C26	2	470pF 0.22uF	CAP, CERM, 470 pF, 50 V, +/- 10%, X7R, 0603 CAP, CERM, 0.22 μF, 25 V, +/- 10%, X5R, 0603	0603 0603	C0603C471K5RACTU GRM188R61E224KA88	Kemet MuRata		
			·		D			
C16 C17	1	0.1uF 4.7uF	CAP, CERM, 0.1 μF, 25 V, +/- 5%, X7R, 0603 CAP, CERM, 4.7 μF, 25 V, +/- 10%, X5R, 0603_095	0603 0603_095	C0603C104J3RACTU GRM188R61E475KE11	Kemet MuRata		
C18, C24,	4	0.01uF	CAP, CERM, 0.01 μF, 25 V, +/- 10%, X7R, 0603	0603	D GRM188R71E103KA01	MuRata		
C25, C28			·	0603	D	MuRata		
C22	1	1000pF	CAP, CERM, 1000 pF, 50 V, +/- 10%, X7R, 0603		D			
C29 C30	1	680pF 1000pF	CAP, CERM, 680 pF, 25 V, +/- 5%, C0G/NP0, 0402 CAP, CERM, 1000 pF, 50 V, +/- 10%, X7R, 0603	0402 0603	C1005C0G1E681J C0603X102K5RACTU	TDK Kemet		
C31	1	0.012uF	CAP, CERM, 0.012 µF, 25 V, +/- 5%, X7R, 0603	0603	06033C123JAT2A	AVX		
C32 C33	1	18pF 27pF	CAP, CERM, 18 pF, 50 V, +/- 5%, C0G/NP0, 0603 CAP, CERM, 27 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603 0603	C1608C0G1H180J 06035A270JAT2A	TDK AVX		
C34	1	120pF	CAP, CERM, 120 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603	GRM1885C1H121JA01	MuRata		
C35, C44,	9	4.7uF	CAP, CERM, 4.7 μF, 25 V, +/- 10%, X5R, 0805	0805	C2012X5R1E475K125A	TDK		
C47, C49, C51, C53,					В			
C55, C65,								
C67 C36, C45	2	0.1uF	CAP, CERM, 0.1 μF, 16 V, +/- 10%, X7R, 0402	0402	GCM155R71C104KA55	MuRata		
C37	1	10uF	CAP, CERM, 10 μF, 16 V, +/- 20%, X5R, 0603	0603	D EMK107BBJ106MA-T	Taiyo Yuden		
C38, C40, C41, C42,	5	2.2uF	CAP, CERM, 2.2 μF, 16 V, +/- 10%, X5R, 0603	0603	GRM188R61C225KAAD			
C43								
C39, C46, C48, C50,	9	47uF	CAP, CERM, 47 μF, 10 V, +/- 10%, X7R, 1210	1210	GRM32ER71A476KE15	MuRata		
C52, C54,								
C56, C66, C68								
C57, C58, C59, C60,	8	2.2uF	CAP, CERM, 2.2 µF, 6.3 V, +/- 20%, X5R, 0402	0402	GRM155R60J225ME15	MuRata		
C61, C62,					D			
C63, C64 C69	1	0.1uF	CAP, CERM, 0.1 µF, 16 V, +/- 10%, X5R, 0603	0603	GRM188R61C104KA01	MuRata		
C70	1	1uF	CAP, CERM, 1 µF, 16 V, +/- 10%, X5R, 0603	0603	D	MuRata		
					D			
C71 C72	1	220pF 0.01uF	CAP, CERM, 220 pF, 50 V, +/- 10%, X7R, 0603 CAP, CERM, 0.01 μF, 10 V, +/- 10%, X5R, 0402	0603 0402	C1608X7R1H221K GRM155R61A103KA01	TDK MuRata		
C73	1	10uF	CAP, CERM, 10 μF, 25 V, +/- 10%, X5R, 0805	0805	D C2012X5R1E106K125A	TDK		
	-		·		В			
C74, C75, C76, C82,	5	10uF	CAP, CERM, 10 μF, 6.3 V, +/- 10%, X7R, 0805	0805	GRM21BR70J106KE76L	MuRata		
C83		0.4.5	DAD OFFILM A F OF W A 4000 MOD OCCU	0000	004050000454044000	TOL		
C77	1	0.1uF	CAP, CERM, 0.1 μF, 25 V, +/- 10%, X8R, 0603	0603	CGA3E2X8R1E104K080 AA	IDK		
C78	1	10pF	CAP, CERM, 10 pF, 100 V, +/- 5%, C0G/NP0, 0603	0603	GRM1885C2A100JA01D	MuRata		
C79, C80,	3	1000pF	CAP, CERM, 1000 pF, 50 V, +/- 1%, C0G/NP0, 0603	0603	GRM1885C1H102FA01J	MuRata		
C81 D1, D2	2	45V	Diode, Schottky, 45 V, 15 A, CFP15	CFP15	PMEG045V150EPDAZ	NXP Semiconductor		
D3 D4	1	Super Red Green	LED, Super Red, SMD LED, Green, SMD	LED, 1.6x.6x.8mm 1.7x0.65x0.8mm	SML-LX0603SRW-TR LG L29K-G2J1-24-Z	Lumex OSRAM		
H1, H2, H3,	4	Orceri	Bumpon, Hemisphere, 0.375 X 0.235, Black	Black Bumpon	SJ61A2	3M		
H4 H5, H6	2		WASHER FLAT 1/4 NYLON	0.260"ID x 0.437"OD x	3218	Keystone	-	-
J1	1		BANANA JACK, SOLDER LUG, RED, TH	0.062"THK Red Insulated Banana	SPC15363	Tenma		
				Jack				
J2	1		BANANA JACK, SOLDER LUG, BLACK, TH	Black Insulated Banana Jack	SPC15354	Tenma		
J3 J4, J5	1 2		Header, 100mil, 12x1, Gold, TH Header, 100mil, 2x1, Gold, TH	12x1 Header Header, 100mil, 2x1,	TSW-112-07-G-S HTSW-102-07-G-S	Samtec Samtec		
		4 0 11		TH				
L1	1	1.8uH	Inductor, Shielded Drum Core, Superflux, 1.8uH, 16A, 0.0035 ohm, SMD	WE-HC6	744325180	Wurth Elektronik eiSos		
L2	1	10uH	Inductor, Shielded Drum Core, Powdered Iron, 10uH, 3A, 0.102 ohm, SMD	IHLP-2525CZ	IHLP2525CZER100M01	Vishay-Dale		
L3	1	4.7uH	Inductor, Shielded Drum Core, Powdered Iron, 4.7uH,	IHLP-2525CZ	IHLP2525CZER4R7M01	Vishay-Dale		
L4, L5, L6,	9	1uH	5.5A, 0.037 ohm, SMD Inductor, Shielded Drum Core, Powdered Iron, 1 µH, 4	4.7x1.2x4.3mm	IHLP1616ABER1R0M01	Vishay-Dale		
L7, L8, L9, L10, L11,			A, 0.05 ohm, SMD					
L12		001/	MODELL BOW SO V SO V SECTION	DDAK	OUDSODOS ASI TO	Victory Con 1		News
Q1 Q2, Q3, Q5,	4	-60V 40V	MOSFET, P-CH, -60 V, -50 A, DPAK MOSFET, N-CH, 40 V, 19 A, SOIC-8	DPAK SOIC-8	SUD50P06-15L-E3 Si4840BDY-T1-GE3	Vishay-Semiconductor Vishay-Siliconix		None None
Q6 Q4	1	40V	MOSFET, N-CH, 40 V, 42 A, DPAK	DPAK	IRLR3114ZTRPBF	International Rectifier		None
R1	1	0.022	RES, 0.022, 1%, 1 W, 0612	0612	PRL1632-R022-F-T1	Susumu Co Ltd		
R3 R4	1	432k 1.50k	RES, 432 k, 1%, 0.1 W, 0603 RES, 1.50 k, 1%, 0.1 W, 0603	0603 0603	CRCW0603432KFKEA ERJ-3EKF1501V	Vishay-Dale Panasonic		
R5, R11 R6	2	82.5k 0.015	RES, 82.5 k, 1%, 0.1 W, 0603 RES, 0.015, 1%, 3 W, 4527	0603 4527	CRCW060382K5FKEA WSR3R0150FEA	Vishay-Dale Vishay-Dale		
R7	1	49.9k	RES, 49.9 k, 0.1%, 0.1 W, 0603	0603	RG1608P-4992-B-T5	Susumu Co Ltd		
R8 R10	1	0.015 255k	RES, 0.015, 1%, 1 W, 0612 RES, 255 k, 1%, 0.1 W, 0603	0612 0603	PRL1632-R015-F-T1 CRCW0603255KFKEA	Susumu Co Ltd Vishay-Dale		
R12 R13	1	1.0k 39k	RES, 1.0 k, 5%, 0.1 W, 0603	0603	CRCW06031K00JNEA RC0603JR-0739KL	Vishay-Dale		
R14	1	27.0k	RES, 39 k, 5%, 0.1 W, 0603 RES, 27.0 k, 0.5%, 0.1 W, 0603	0603 0603	RT0603DRD0727KL	Yageo America Yageo America		
R15, R20, R25	3	10.0k	RES, 10.0 k, 1%, 0.1 W, 0603	0603	RC0603FR-0710KL	Yageo America		
R16, R17,	4	2.2k	RES, 2.2 k, 5%, 0.063 W, 0402	0402	CRCW04022K20JNED	Vishay-Dale		
R18, R19 R23, R24	2	0	RES, 0, 5%, 0.063 W, 0402	0402	RC0402JR-070RL	Yageo America		
R26, R29, R30	3	10.0k	RES, 10.0 k, 1%, 0.1 W, 0603	0603	CRCW060310K0FKEA	Vishay-Dale		
R27	1	100k	RES, 100 k, 5%, 0.1 W, 0603	0603	CRCW0603100KJNEA	Vishay-Dale		
R28	1	10.0	RES, 10.0, 0.1%, 0.1 W, 0603	0603	TNPW060310R0BEEA	Vishay-Dale		

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer	Alternate PartNumber	Alternate Manufacturer
R31		49.9	RES, 49.9, 1%, 0.1 W, 0603	0603	RC0603FR-0749R9L	Yageo America		
R32	1	806	RES, 806, 1%, 0.1 W, 0603	0603	CRCW0603806RFKEA	Vishav-Dale		
S1	1		Switch, 4PST, 0.25 A, 120 V, TH	12.6x12.6mm	15451	MEC Switches		
TP1, TP5,	14		PCB Pin, Swage Mount, TH	PCB Pin(2505-2)	2505-2-00-44-00-00-07-	Mill-Max		
TP16, TP17,					0			
TP18, TP19,								
TP20, TP21,								
TP22, TP23,								
TP24, TP25,								
TP26, TP27								
TP3, TP4	2	Black	Test Point, Compact, Black, TH	Black Compact	5006	Keystone		
0,	-	Black	root rom, compact, black, m	Testpoint	0000	rioyolorio		
TP6, TP8,	4	White	Test Point, Miniature, White, TH	White Miniature	5002	Keystone		
TP11, TP12				Testpoint		-		
U1	1		LOW IQ, SINGLE BOOST, DUAL SYNCHRONOUS	DAP0038B	TPS43330AQDAPRQ1	Texas Instruments		Texas Instruments
			BUCK CONTROLLER, DAP0038B					
U2	1		Automotive Power Management Unit (PMU) for	ZWS0169A	O9039A360IZWSRQ1	Texas Instruments		Texas Instruments
			Processor, ZWS0169A					
U3	1		5.5-V, 4-A, 16-mO On-Resistance Load Switch,	DSG0008A	TPS22965TDSGRQ1	Texas Instruments	TPS22965TDSGTQ1	Texas Instruments
U4	1		DSG0008A Single Output Automotive LDO, 3 A, 2.3 to 3.5 V Input,	DRC0010A	TPS51200QDRCRQ1	Texas Instruments	Control of	None
04	1			DRC0010A	1P551200QDRCRQ1	l exas instruments	Equivalent	None
			with DDR Termination, 10-pin SON (DRC), -40 to 125 degC, Green (RoHS & no Sb/Br)					
C2	0	220uF	CAP, AL, 220 µF, 63 V, +/- 20%, 0.26 ohm, SMD	SMT Radial H13	EEE-TK1J221AQ	Panasonic		
C5	0	560uF	CAP, AL, 560 uF, 50 V, +/- 20%, 0.05 ohm, TH	D12.5xL25mm	EEU-FC1H561	Panasonic		
C11	0	1000pF	CAP, CERM, 1000 pF, 25 V, +/- 5%, C0G/NP0, 0603	0603	GRM1885C1E102JA01D			
	,		2 , 22, 122 p. , 22 1, 17 6/6, 666/11 6, 6666					
C23	0	1000pF	CAP, CERM, 1000 pF, 50 V, +/- 10%, X7R, 0603	0603	GRM188R71H102KA01	MuRata		
			, , , , , , , , , , , , , , , , , , , ,		D			
FID1, FID2,	0		Fiducial mark. There is nothing to buy or mount.	Fiducial	N/A	N/A		
FID3, FID4,								
FID5, FID6								
R2, R9	0	10.0	RES, 10.0, 1%, 0.1 W, 0603	0603	CRCW060310R0FKEA	Vishay-Dale		
R21, R22	0	0	RES, 0, 5%, 0.063 W, 0402	0402	RC0402JR-070RL	Yageo America		

## Notes:

Unless otherwise noted in the Alternate PartNumber and/or Alternate Manufacturer columns, all parts may be substituted with equivalents.

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